

**IN THE UNITED STATES PATENT AND TRADEMARK OFFICE**

Applicant(s): MASUDA, et al  
Serial No.: (not yet assigned)  
Filed: July 11, 2003  
For: PLASMA ETCHING APPARATUS AND PLASMA ETCHING METHOD

**INFORMATION DISCLOSURE STATEMENT**  
**UNDER 37 CFR 1.97 & 1.98**

Mail Stop DD  
Commissioner for Patents  
P.O. Box 1450  
Alexandria, VA 22313-1450

July 11, 2003

Sir:

In the matter of the above-identified application, this information disclosure statement is being submitted with the following citation as specified in 37 CFR 1.97(d).

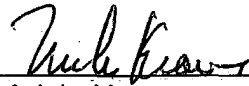
"A copy of any patent, publication or other information listed in an information disclosure statement is not required to be provided if it was previously cited by or submitted to the Office in a prior application, provided that the prior application is properly identified in the statement and relied upon for an earlier filing date under 35 U.S.C. 120."

Applicant(s) are submitting herewith a copy of Form PTO-1449 which list documents cited in parent application(s) Serial No. 09/983,946, filed October 26, 2001, Serial No. 09/421,044, filed October 20, 1999, Serial No. 09/227,332, filed January 8, 1999, now U.S. Patent No. 6,171,438, Serial No. 08/611,758, filed March 8, 1996, now U.S. Patent No. 5,874,012.

It is respectfully requested that this information disclosure statement be considered by the Examiner.

Please charge any shortage in the fees due in connection with the filing of this paper, including extension of time fees, to Deposit Account No. 01-2135 (520.34403C10) and please credit any excess fees to such deposit account.

Respectfully submitted,

A handwritten signature in dark ink, appearing to read "Melvin Kraus", is written over a horizontal line.

Melvin Kraus

Registration No. 22,466

ANTONELLI, TERRY, STOUT & KRAUS, LLP

MK/cee  
(703) 312-6600

U.S. Patent Documents

Examiner Initials	Document No.	Date	Name	Class Subclass	Filing Date If Approp.
	4,209,357	6/80	Gorin et al		
	5,283,414	2/94	Straemke (corresponds to DE 40 07 123 A1)		
	5,290,381	3/94	Nozawa et al		
	5,356,672	10/94	Schmitt, III et al		
	5,362,361	11/94	Tatsumi		
	5,366,585	11/94	Robertson et al		
	5,445,709	8/95	Kojima et al		
	5,478,429	12/95	Komino et al		
	5,647,945	7/97	Matsuse et al		
	5,651,826	7/97	Takagi		
	5,756,400	5/98	Ye et al		
	5,874,012	2/99	Kanai et al		
	6,068,784	5/00	Collins et al		
	6,171,438	1/01	Masuda et al		

Foreign Patent Documents

Document No.	Date	Country	Class Subclass	Translation Yes No
56-67925	6/81	Japan		
57-23228	2/82	Japan		
58-153332	9/83	Japan		
59-144132	8/84	Japan		
62-95828	5/87	Japan		
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0 272 140 B1	2/94	European		
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Form PTO-1449  
Equivalent

U.S. Department of Commerce  
Patent and Trademark Office

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Group:  
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Foreign Patent Documents

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0 648 858 A1	4/95	European			
7-147247	6/95	Japan			
7-312363	11/95	Japan			
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0 688 037 B1	12/95	European			
8-51099	2/96	Japan			
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8-186093	7/96	Japan			
0 734 047 A2	9/96	European			
9-157832	5/97	Japan			
9-275092	10/97	Japan			

Other Documents (including Author, Title, Date, Pertinent Pages, etc.)

"Suppression Shield for RF Plasma", W. J. Curry et al, IBM Technical Disclosure Bulletin, Vol. 22, No. 11, April 1980, pp 4909-4910

Examiner

Date Considered

\*Examiner: Initial if reference considered, whether or not citation is in conformance with MPEP 609; Draw line through citation if not in conformance and not considered. Include copy of this form with next communication to applicant.